

ABSTRACT OF THE DISCLOSURE

An addition curing type silicone resin composition is provided including (A) 100 parts by weight of a specific organopolysiloxane with a phenyl group and at least two alkenyl groups within each molecule, (B) 1 to 100 parts by weight of a specific organohydrogenpolysiloxane with a phenyl group and at least two SiH groups within each molecule, and (C) an effective quantity of a hydrosilylation reaction catalyst. A cured product obtained by curing this composition is transparent, displays good strength and particularly good flexural strength, and moreover also displays a high degree of hardness. The composition is applicable to a variety of fields including electrical and electronic equipment, OA equipment and precision instruments.